Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	<u>ti.com/support</u>
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	06/12/2022

Details for "TPS7A0527PDBZT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A0527PDBZT	SN	Level-1-260C-UNLIM	Ext-Mfg	DBZ 3	2.9x1.3x0.95	13.6

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
Component				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.029818	100	1000000	0.218574	2186
Sub-Total			0.029818	100	1000000	0.218574	2186
Die Attach Adhesive	-						
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.009367	30.00032	300003	0.068663	687
Other Inorganic Materials	Silica	7631-86-9	0.001405	4.499888	44999	0.010299	103
Other Organic Materials	Chlorine	7782-50-5	0.000011	0.03523	352	0.000081	1
Thermoplastics	Ероху	85954-11-6	0.02044	65.464561	654646	0.149831	1498
Sub-Total			0.031223	100	1000000	0.228873	2289
Lead Frame	•		•		•		,
Copper and Its Alloys	Copper	7440-50-8	5.886125	94.9375	949375	43.146871	431469
Copper and Its Alloys	Iron	7439-89-6	0.1457	2.35	23500	1.06802	10680
Copper and Its Alloys	Phosphorus	7723-14-0	0.005115	0.0825	825	0.037494	375
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00031	0.005	50	0.002272	23
Precious Metals	Silver	7440-22-4	0.155	2.5	25000	1.136191	11362
Zinc and Its Alloys	Zinc	7440-66-6	0.00775	0.125	1250	0.05681	568
Sub-Total			6.2	100	1000000	45.447658	454477
Lead Frame Plating		-			· · · · · · · · · · · · · · · · · · ·		
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.38	100	1000000	10.115769	101158
Sub-Total			1.38	100	1000000	10.115769	101158
Mold Compound	-						
Other Inorganic Materials	Fused Silica	60676-86-0	5.046646	86.850001	868500	36.993265	369933
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.029054	0.500003	5000	0.212974	2130
Other Plastics and Rubber	Carbon Black	1333-86-4	0.008716	0.149998	1500	0.063891	639
Thermoplastics	Ероху	85954-11-6	0.726345	12.499998	125000	5.324303	53243
Sub-Total			5.810761	100	1000000	42.594432	425944
Semiconductor Device	•	-			•		
Ceramics / Glass	Doped Silicon	7440-21-3	0.190265	100	1000000	1.394693	13947
Sub-Total			0.190265	100	1000000	1.394693	13947
Total			13 642067			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.